



## Customer Information Notification

2024040271 : PF8xxx New Products with NXP ATTJ Assembly Site Sourcing and Dimple Wettable Flank QFN

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Nov 02, 2024 **Effective Date:** Nov 03, 2024

Here is your personalized communication about an NXP notification.  
For detailed information we invite you to [view this notification online](#)

### Management summary

New PF8xxx product offerings with assembly sourced from NXP ATTJ Tianjin China, including dimple wettable flank QFN, for customer supply assurance.

### Change Category

- |  |   |  |   |   |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials  | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location   | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input checked="" type="checkbox"/> Other: Data Sheet Update (Technical Clarifications / Corrections) |  |   |   |

### Notification Overview

#### Description

---

NXP Semiconductors announces the assembly site expansion with optimized QFN package for the PF8xxx Power Management IC devices associated with this notification, from current ASECL Taiwan assembly site to NXP ATTJ Tianjin China assembly site. The QFN package changes from step-cut wettable flank / non-wettable flank to dimple wettable flank version. Product data sheets are updated to document new orderable part numbers with dimple QFN and package outline drawings, along with other technical clarifications and corrections, as detailed in the data sheets revision history section.

New PF8xxx part numbers are offered for the NXP ATTJ assembled dimple QFN products.

The assembly site expansion to NXP ATTJ results in the following change summary:

- Change to dimple wettable flank QFN package from step-cut wettable flank QFN / non-wettable flank QFN package
- Change to 7mil die thickness from 5mil die thickness
- Change to PPF lead frame from Cu lead frame with Sn plating
- Change to Henkel QMI519 die attach material from Hitachi EN4900
- Change to Hitachi CEL9220HF13CW mold compound material from Sumitomo G700LA
- Change of package outline drawing to incorporate standardized NXP ATTJ QFN package
- No change to wire type or wire diameter: identical at both assembly sites (PdCu / 33 um)
- No change to PCB solder mask pattern / stencil

The assembly site expansion to NXP ATTJ was successfully qualified adhering to NXP specifications.

Current ASECL step-cut wettable flank QFN package outline drawing 98ASA01086D / SOT684-21(DD/SC) is attached to this notification and can be found at the NXP site:

[https://www.nxp.com/docs/en/package-information/SOT684-21\(DDSC\).pdf](https://www.nxp.com/docs/en/package-information/SOT684-21(DDSC).pdf)

Current ASECL non-wettable flank QFN package outline drawing 98ASA01332D / SOT684-21 is attached to this notification and can be found at the NXP site:

<https://www.nxp.com/docs/en/package-information/SOT684-21.pdf>

New ATTJ dimple QFN package outline drawing 98ASA01750D / SOT684-29(D) is attached to this notification and can be found at the NXP site:

[https://www.nxp.com/docs/en/package-information/SOT684-29\(D\).pdf](https://www.nxp.com/docs/en/package-information/SOT684-29(D).pdf)

Data sheets are updated to document new orderable part numbers with dimple QFN and package outline drawings, along with other technical clarifications and corrections.

The revision history included in the updated data sheets provides a detailed description of the changes.

New PF8100\_PF8200 data sheet revision 12.0 is attached to this notification and can be found at the NXP site: [https://www.nxp.com/docs/en/data-sheet/PF8100\\_PF8200.pdf](https://www.nxp.com/docs/en/data-sheet/PF8100_PF8200.pdf)

New PF8101\_PF8201 data sheet revision 5.0 is attached to this notification and can be found at the NXP site: [https://www.nxp.com/docs/en/data-sheet/PF8101\\_PF8201.pdf](https://www.nxp.com/docs/en/data-sheet/PF8101_PF8201.pdf)

New PF8121 data sheet revision 6.0 is attached to this notification and can be found at the NXP site: <https://www.nxp.com/docs/en/data-sheet/PF8121.pdf>

Please see the attached files for additional details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-01, SEM-PA-04, SEM-PA-07, SEM-PA-11, SEM-PA-18, SEM-PW-03, SEM-DS-02

### **Reason**

Qualification of NXP ATTJ Tianjin China assembly site with dimple wettable flank QFN optimization is required for customer supply assurance.

### **Identification of Affected Products**

New part numbers are created for NXP ATTJ Tianjin assembled dimple QFN products. Product assembly site, among other information, is reflected in the part marking trace code.

Please refer to the marking comparisons in the change summary attachment.

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

---

No impact to function, reliability or quality. Updates to form and fit as described in the accompanying documentation.

### **Data Sheet Revision**

A new data sheet will be issued

### **Disposition of Old Products**

PF8xxx product associated with this notification will be dual sourced from ASECL Taiwan assembly site and from NXP ATTJ Tianjin China assembly site. Some products will become not recommended for new designs. Please see details in the attached product data sheets.

### **Additional information**

---

Additional documents: [view online](#)

## Contact and Support

---

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

<b>Name</b>	Anqi Jiang
<b>Position</b>	Product Engineer
<b>e-mail address</b>	<a href="mailto:anqi.jiang@nxp.com">anqi.jiang@nxp.com</a>

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

### About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

---

NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2024 NXP Semiconductors. All rights reserved.